

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes: a semiconductor element 2 bonded on a first metallic layer; a wire 4 for electrically connecting an electrode pad of the semiconductor element to a second metallic layer; and a resin package 7 for sealing said semiconductor element. Rear surfaces of the first metallic layer 8a and the second metallic layer 8b are flush with a bottom of said resin package.

P U R E F I C A T I O N - P U R E F I C A T I O N

10